



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Richard W. Wensel

**Serial No.:** 10/077,452

**Filed:** February 14, 2002

**For:** METHOD AND APPARATUS FOR  
TRANSFER MOLDING  
ENCAPSULATION OF A  
SEMICONDUCTOR DIE WITH  
ATTACHED HEAT SINK

**Confirmation No.:** 4093

**Examiner:** D. Graybill

**Group Art Unit:** 2827

**Attorney Docket No.:** 2269-3061.6US  
(96-0893.05/US)

**Notice of Allowance Mailed:**

June 22, 2004

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Person making Deposit: Christopher Haughton

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** appear on page 3 of this paper.

A **Listing of the Claims** begins on page 4 of this paper.

**Amendments to the Drawings** appear on page 7 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

**Remarks** begin on page 8 of this paper.

An **Appendix** including amended drawing figures is attached following page 8 of this paper.